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Date: July 9, 2004

IN THE WNITED STATES PATENT AND TRADEMARK OFFICE

Applic. No.

10/806,512

Confirmation No: 3891

Applicant

Maik Stegemann, et al.

Filed

March 22, 2004

Art Unit

2811

Title

Method for Fabricating a Semiconductor Structure

Docket No.

RSW-S3019

Customer No.

24131

LETTER

Mail Stop: Missing Parts Commissioner for Patents, Alexandria, VA 22313-1450

Sir:

The above-mentioned new patent application was filed on March 22, 2004 without a signed oath or declaration, under the provision of 37 C.F.R. 1.53(f).

In accordance with the above-mentioned rule, the signed declaration was filed in the Patent Office with a mailing certificate and the surcharge on April 30, 2004.

Enclosed herewith is a copy of the signed declaration that was filed.

Counsel has now received a Notice to File Missing Parts of Application, dated June 7, 2004. However, as mentioned above, the original signed declaration has already been filed.

We authorized the U.S. Patent Office to charge our account on April 30, 2004 when we submitted a credit card slip with the declaration for \$130.00. However, our account was never charged so we again authorize you to charge \$130.00.

Respectfully submitted,

KYLENH. FLINDT **REG NO. 42,539**

Date: July 9, 2004

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/av



COMBINED DECLARATION AND POWER OF ATTORNEY IN ORIGINAL APPLICATION

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

METHOD FOR FABRICATING A SEMICONDUCTOR STRUCTURE

described and claimed in the specification bearing that title, that I understand the content of the specification, that I do not know and do not believe the same was ever known or used in the United States of America before my or our invention thereof, or patented or described in any printed publication in any country before my or our invention thereof or more than one year prior to this application, that the same was not in public use or on sale in the United States of America more than one year prior to this application, that the invention has not been patented or made the subject of an inventor's certificate issued before the date of this application in any country foreign to the United States of America on an application filed by me or my legal representatives or assigns more than tweive months prior to this application, that I acknowledge the duty to disclose to the Office all information known to me to be material to patentability as defined in 37 CFR § 1.56, and that no application for patent or inventor's certificate of this invention has been filed earlier than the following in any country foreign to the United States prior to this application by me or my legal representatives or assigns:

German: Application 103 12 469.1, filed March 20, 2003, the International Priority of which is claimed under 35 U.S.C. § 119.

I hereby appoint practitioners associated with the Customer Number

24131

as my attorneys and/or agents to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith.

Address all correspondence and telephone calls to:

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I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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